

### **REMARKS/ARGUMENTS**

The present amendment is in response to the Office Action received on December 15, 2005, in which claims 30, 31, and 34-41 were rejected. Applicant has thoroughly reviewed the outstanding Office Action including the Examiner's remarks and the reference cited therein. The following remarks are believed to be fully responsive to the Office Action and render all claims at issue patentably distinguishable over the cited references. Claims 1-29, 32-33, and 42-27 have been previously withdrawn as unelected claims. Claims 34 and 36 have been amended by the present amendment, while claims 30-31, 35, and 37-41 are unchanged. Reconsideration and withdrawal of the rejections set forth in the Office Action dated December 15, 2005 are respectfully requested.

#### **Claim Rejections - 35 U.S.C. § 112**

The Examiner has rejected claims 34 and 36 under 35 U.S.C. 112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter which applicant regards as the invention. Appropriate corrections have been made by amendment. Accordingly, it is respectfully requested that the Examiner now withdraw the 35 U.S.C. 112, second paragraph rejection.

#### **Claim Rejections - 35 U.S.C. § 103**

The Examiner has rejected claims 30-31 and 34-41 as being obvious in view of the combined teachings of U.S. Patent Application Publication No. 2003/0122243 to Lee et al. It is respectfully submitted that Lee et al. fails to teach or suggest the applicant's invention as defined by the present claims.

The present invention provides a fan out type package structure. With reference to independent claim 30, the package structure of the claimed invention comprises a first contact conductive layer formed on the first openings to electrically coupling with the first pads, respectively. The first conductive lines are formed on the first contact conductive layer after forming the first contact conductive layer. The preferable material of the first contact conductive layer may be Ti, Cu or the combination thereof (see claim 37), and therefore the first contact conductive layer can be employed as a buffer and enhance the adhesion between the first conductive lines and the first pads.

The Examiner argues that Lee et al. teaches a first contact conductive layer 142b that is formed on the first openings to electrically coupling with the first pads, respectively, shown in FIG. 1d of Lee et al. Applicant respectfully disagrees with the Examiner's argument. In this regard, reference is made to paragraph [0035] of Lee et al., where Lee et al. recites that wherein part of the conductive material from patterned wiring layer 144 will be injected into thru-holes 142a to form vias 142b. Therefore, the vias 142b is simultaneously formed with the patterned wiring layer 144 in the same manufacturing process. The vias 142b is actually a via instead of a contact conductive layer. In fact, vias 142b is actually not a contact conductive layer. In contrast to the teachings of Lee et al., in the present invention, the first contact conductive layer is individually formed into the openings by performing a process, and the first conductive lines are also individually formed on the first contact conductive layer by performing another process after the formation of the contact conductive layer. Double layer structure including the first contact conductive layer and first conductive lines of the present invention is provided. In other words, the package structure of Lee et al. does not expressly include a first contact conductive layer, and the vias 142b is simultaneously formed with the patterned wiring layer 144 in the same process. Therefore, Lee et al. fails to teach or suggest a first contact conductive layer that is formed on the first openings to electrically couple with the first pads.

In conclusion, it is respectfully submitted that Lee et al. fails to teach a significant feature of the claimed invention. Furthermore, Lee et al. does not disclose, teach or motivate the technical feature of above-mentioned "a first contact conductive layer is formed on the first openings to electrically couple with the first pads." Furthermore, the first conductive lines of the package structure of Lee et al. is formed on the second dielectric layer and the corresponding first contact conductive layer after forming the first contact conductive layer. Therefore, it is respectfully submitted that claim 30 is non-obvious and patentable in view of Lee et al., since "absence of property which a claimed invention would have been expected to possess based on the teachings of the prior art is evidence of unobviousness." *Ex parte Mead Johnson & Co.* 227 USPQ 78 (Bd. Pat. App. & Inter. 1985).

In addition, the first contact conductive layer of the present invention can be employed as a buffer for reducing the stress and enhancing the adhesion between the first

conductive lines and the first pads. Therefore, claim 30 is non-obvious and patentable in view of the citation of Lee et al.

Since claims 31, and 34-41 depend from independent claim 30, it is respectfully submitted that these claims should likewise be patentable upon the patentability of claim 30.

The result of the claims invention is unexpected over the prior art. Applicant believes that the present response traverses the rejection under 35 U.S.C. 103. Accordingly, reconsideration and withdrawal of the prior art rejections under 35 U.S.C. 103 set forth in the Office Action is respectfully requested.

**Conclusion**

In view of the foregoing, claims 30, 31, and 34-41, now pending in the application, comply with the requirement of patentability by defining over the cited reference. A Notice of Allowance is, therefore, respectfully requested.

The cited references made of record and not relied upon have also been reviewed. It is respectfully submitted that none of these additional references teaches or suggests the applicants' invention as defined by the present claims.

If there are any fees necessitated by the foregoing communication, please charge such fees to our Deposit Account No. 50-0537, referencing our Docket No. HK9225US.

Date: **March 15, 2006**

Respectfully submitted,



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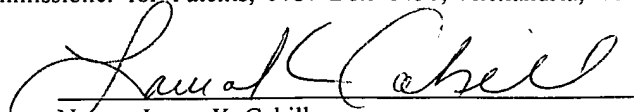
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Date: **March 15, 2006**

  
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